

Low Viscosity Adhesive/Sealant Cures at Room Temperature

This easy-to-use, two-component epoxy adhesive called EP30 is provided for high performance bonding applications. It develops excellent physical strength properties even when cured at ambient temperatures. Cure can be accelerated by use of moderate heat. EP30 features very low viscosity along with excellent chemical resistance, dimensional stability, hardness, and optical clarity. Electrical insulation properties are provided even upon prolonged exposure to moisture. EP30 is widely used in potting and encapsulating electronic components as well as in bonding optical elements. For medical applications, a USP Class VI approved version called EP30MED is available.

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<http://www.mdtmag.com/product-releases/2008/10/low-viscosity-adhesive/sealant-cures-room-temperature>